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LCD TV

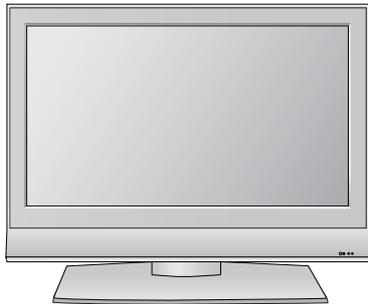
SERVICE MANUAL

CHASSIS : LP78A

MODEL : 32LC7R 32LC7R-ZA
32LC51 32LC51-ZA
32LC52 32LC52-ZC

CAUTION

BEFORE SERVICING THE CHASSIS,
READ THE SAFETY PRECAUTIONS IN THIS MANUAL.



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SERVICING PRECAUTIONS

CAUTION: Before servicing receivers covered by this service manual and its supplements and addenda, read and follow the *SAFETY PRECAUTIONS* on page 3 of this publication.

NOTE: If unforeseen circumstances create conflict between the following servicing precautions and any of the safety precautions on page 3 of this publication, always follow the safety precautions. Remember: Safety First.

General Servicing Precautions

1. Always unplug the receiver AC power cord from the AC power source before;
 - a. Removing or reinstalling any component, circuit board module or any other receiver assembly.
 - b. Disconnecting or reconnecting any receiver electrical plug or other electrical connection.
 - c. Connecting a test substitute in parallel with an electrolytic capacitor in the receiver.
CAUTION: A wrong part substitution or incorrect polarity installation of electrolytic capacitors may result in an explosion hazard.
2. Test high voltage only by measuring it with an appropriate high voltage meter or other voltage measuring device (DVM, FETVOM, etc) equipped with a suitable high voltage probe. Do not test high voltage by "drawing an arc".
3. Do not spray chemicals on or near this receiver or any of its assemblies.
4. Unless specified otherwise in this service manual, clean electrical contacts only by applying the following mixture to the contacts with a pipe cleaner, cotton-tipped stick or comparable non-abrasive applicator; 10% (by volume) Acetone and 90% (by volume) isopropyl alcohol (90%-99% strength)
CAUTION: This is a flammable mixture.
Unless specified otherwise in this service manual, lubrication of contacts is not required.
5. Do not defeat any plug/socket B+ voltage interlocks with which receivers covered by this service manual might be equipped.
6. Do not apply AC power to this instrument and/or any of its electrical assemblies unless all solid-state device heat sinks are correctly installed.
7. Always connect the test receiver ground lead to the receiver chassis ground before connecting the test receiver positive lead.
Always remove the test receiver ground lead last.
8. *Use with this receiver only the test fixtures specified in this service manual.*
CAUTION: Do not connect the test fixture ground strap to any heat sink in this receiver.

Electrostatically Sensitive (ES) Devices

Some semiconductor (solid-state) devices can be damaged easily by static electricity. Such components commonly are called *Electrostatically Sensitive (ES) Devices*. Examples of typical ES devices are integrated circuits and some field-effect transistors and semiconductor "chip" components. The following techniques should be used to help reduce the incidence of component damage caused by static by static electricity.

1. Immediately before handling any semiconductor component or semiconductor-equipped assembly, drain off any electrostatic charge on your body by touching a known earth ground. Alternatively, obtain and wear a commercially available discharging wrist strap device, which should be removed to prevent potential shock reasons prior to applying power to the

unit under test.

2. After removing an electrical assembly equipped with ES devices, place the assembly on a conductive surface such as aluminum foil, to prevent electrostatic charge buildup or exposure of the assembly.
3. Use only a grounded-tip soldering iron to solder or unsolder ES devices.
4. Use only an anti-static type solder removal device. Some solder removal devices not classified as "anti-static" can generate electrical charges sufficient to damage ES devices.
5. Do not use freon-propelled chemicals. These can generate electrical charges sufficient to damage ES devices.
6. Do not remove a replacement ES device from its protective package until immediately before you are ready to install it. (Most replacement ES devices are packaged with leads electrically shorted together by conductive foam, aluminum foil or comparable conductive material).
7. Immediately before removing the protective material from the leads of a replacement ES device, touch the protective material to the chassis or circuit assembly into which the device will be installed.
CAUTION: Be sure no power is applied to the chassis or circuit, and observe all other safety precautions.
8. Minimize bodily motions when handling unpackaged replacement ES devices. (Otherwise harmless motion such as the brushing together of your clothes fabric or the lifting of your foot from a carpeted floor can generate static electricity sufficient to damage an ES device.)

General Soldering Guidelines

1. Use a grounded-tip, low-wattage soldering iron and appropriate tip size and shape that will maintain tip temperature within the range or 500°F to 600°F.
2. Use an appropriate gauge of RMA resin-core solder composed of 60 parts tin/40 parts lead.
3. Keep the soldering iron tip clean and well tinned.
4. Thoroughly clean the surfaces to be soldered. Use a mall wire-bristle (0.5 inch, or 1.25cm) brush with a metal handle. Do not use freon-propelled spray-on cleaners.
5. Use the following unsoldering technique
 - a. Allow the soldering iron tip to reach normal temperature. (500°F to 600°F)
 - b. Heat the component lead until the solder melts.
 - c. Quickly draw the melted solder with an anti-static, suction-type solder removal device or with solder braid.
CAUTION: Work quickly to avoid overheating the circuit board printed foil.
6. Use the following soldering technique.
 - a. Allow the soldering iron tip to reach a normal temperature (500°F to 600°F)
 - b. First, hold the soldering iron tip and solder the strand against the component lead until the solder melts.
 - c. Quickly move the soldering iron tip to the junction of the component lead and the printed circuit foil, and hold it there only until the solder flows onto and around both the component lead and the foil.
CAUTION: Work quickly to avoid overheating the circuit board printed foil.
 - d. Closely inspect the solder area and remove any excess or splashed solder with a small wire-bristle brush.

IC Remove/Replacement

Some chassis circuit boards have slotted holes (oblong) through which the IC leads are inserted and then bent flat against the circuit foil. When holes are the slotted type, the following technique should be used to remove and replace the IC. When working with boards using the familiar round hole, use the standard technique as outlined in paragraphs 5 and 6 above.

Removal

1. Desolder and straighten each IC lead in one operation by gently prying up on the lead with the soldering iron tip as the solder melts.
2. Draw away the melted solder with an anti-static suction-type solder removal device (or with solder braid) before removing the IC.

Replacement

1. Carefully insert the replacement IC in the circuit board.
2. Carefully bend each IC lead against the circuit foil pad and solder it.
3. Clean the soldered areas with a small wire-bristle brush. (It is not necessary to reapply acrylic coating to the areas).

"Small-Signal" Discrete Transistor

Removal/Replacement

1. Remove the defective transistor by clipping its leads as close as possible to the component body.
2. Bend into a "U" shape the end of each of three leads remaining on the circuit board.
3. Bend into a "U" shape the replacement transistor leads.
4. Connect the replacement transistor leads to the corresponding leads extending from the circuit board and crimp the "U" with long nose pliers to insure metal to metal contact then solder each connection.

Power Output, Transistor Device

Removal/Replacement

1. Heat and remove all solder from around the transistor leads.
2. Remove the heat sink mounting screw (if so equipped).
3. Carefully remove the transistor from the heat sink of the circuit board.
4. Insert new transistor in the circuit board.
5. Solder each transistor lead, and clip off excess lead.
6. Replace heat sink.

Diode Removal/Replacement

1. Remove defective diode by clipping its leads as close as possible to diode body.
2. Bend the two remaining leads perpendicular y to the circuit board.
3. Observing diode polarity, wrap each lead of the new diode around the corresponding lead on the circuit board.
4. Securely crimp each connection and solder it.
5. Inspect (on the circuit board copper side) the solder joints of the two "original" leads. If they are not shiny, reheat them and if necessary, apply additional solder.

Fuse and Conventional Resistor

Removal/Replacement

1. Clip each fuse or resistor lead at top of the circuit board hollow stake.
2. Securely crimp the leads of replacement component around notch at stake top.
3. Solder the connections.

CAUTION: Maintain original spacing between the replaced component and adjacent components and the circuit board to prevent excessive component temperatures.

Circuit Board Foil Repair

Excessive heat applied to the copper foil of any printed circuit board will weaken the adhesive that bonds the foil to the circuit board causing the foil to separate from or "lift-off" the board. The following guidelines and procedures should be followed whenever this condition is encountered.

At IC Connections

To repair a defective copper pattern at IC connections use the following procedure to install a jumper wire on the copper pattern side of the circuit board. (Use this technique only on IC connections).

1. Carefully remove the damaged copper pattern with a sharp knife. (Remove only as much copper as absolutely necessary).
2. Carefully scratch away the solder resist and acrylic coating (if used) from the end of the remaining copper pattern.
3. Bend a small "U" in one end of a small gauge jumper wire and carefully crimp it around the IC pin. Solder the IC connection.
4. Route the jumper wire along the path of the out-away copper pattern and let it overlap the previously scraped end of the good copper pattern. Solder the overlapped area and clip off any excess jumper wire.

At Other Connections

Use the following technique to repair the defective copper pattern at connections other than IC Pins. This technique involves the installation of a jumper wire on the component side of the circuit board.

1. Remove the defective copper pattern with a sharp knife. Remove at least 1/4 inch of copper, to ensure that a hazardous condition will not exist if the jumper wire opens.
 2. Trace along the copper pattern from both sides of the pattern break and locate the nearest component that is directly connected to the affected copper pattern.
 3. Connect insulated 20-gauge jumper wire from the lead of the nearest component on one side of the pattern break to the lead of the nearest component on the other side. Carefully crimp and solder the connections.
- CAUTION:** Be sure the insulated jumper wire is dressed so the it does not touch components or sharp edges.

SPECIFICATION

NOTE : Specifications and others are subject to change without notice for improvement.

1. Application range

This specification is applied to LP78A chassis.

2. Requirement for Test

Testing for standard of each part must be followed in below condition.

- (1) Temperature : $25 \pm 5^{\circ}\text{C}$ ($77 \pm 9^{\circ}\text{F}$), CST : $40 \pm 5^{\circ}\text{C}$
- (2) Humidity : $65\% \pm 10\%$
- (3) Power : Standard input voltage (100-240V~, 50/60Hz)
*Standard Voltage of each products is marked by models

(4) Specification and performance of each parts are followed each drawing and specification by part number in accordance with BOM.

(5) The receiver must be operated for about 20 minutes prior to the adjustment.

3. Test method

3.1 Performance : LGE TV test method followed

3.2 Demanded other specification

Safety : CE, IEC Specification

EMC : CE, IEC

4. General Specification(LCD Module)

Item	Specification		Measurement	Result	Remark				
Display Screen Device	26/27/32/37/42" wide Color Display Module				LCD				
Aspect Ratio	16:9								
LCD Module	26/27/32/37/42" TFT WXGA LCD				MAKER : AUO/CMO/LPL/CPT				
Operating Environment	Temp. : 0 ~ 40 deg, Humidity : 0 ~ 85%				LGE SPEC				
Storage Environment	Temp. : -20 ~ 60 deg, Humidity : 0 ~ 85 %								
Input Voltage	100-240V~, 50/60Hz								
Power Consumption	Power on (Green) ≤ TBD (42") ≤ max (26", 27", 32", 37")				Volume: 1/8 volume of sound distortion point				
	St-By (Red) : 1.0 W								
LCD Module	AUO	Outline Dimension	26"	626.0 x 373.0 x 47.5	mm	(H) x (V) x (D) [with inverter]			
			32"	760.0 x 450.0 x 45	mm				
			37"	877.0 x 514.6 x 54.7	mm				
		Pixel Pitch	26"	0.4215	mm				
			32"	0.51075					
			37"	0.6 x 0.6			(H) x (W)		
		Back Light	26",32"	8 U-lamp					
			37"	10 U-lamp					
		CMO	Outline Dimension	27"	637.55 x 379.8 x 40.7		mm	(H) x (V) x (D) [with inverter]	
				32"	760 x 450 x 47.53				
			Pixel Pitch	27"	0.1455 x 0.4365		mm		(H) x (V)
				32"	0.1730 x 0.5190				
	Back Light		27"	14 CCFL					
			32"	16 CCFL					
	LPL	Outline Dimension	26"	626 x 373 x 44.1	mm	(H) x (V) x (D) [with inverter] (H) x (V)			
			32"	760.0 x 450.0 x 48.0					
			37"	877.0 x 516.8 x 55.5					
			42"	1006 x 610 x 56					
		Pixel Pitch	26"	0.1405 x 0.4215	mm				
			32"	0.17025 x 0.51075					
			37"	0.200 x 0.600					
			42"	0.227 x 0.681					
		Back Light	26"	18 EEFL (17 EEFL)			(LC260WX2-SLB3)		
			32"	18 EEFL					
37"			20 EEFL						
42"			20 CCFL						
Display Colors		16.7M (16,777,216)			(LPL 26")				
Coating		3H, AG							